

|    | Type | Hits | Search Text   | DBs   |
|----|------|------|---|---|
| 1  | BRS  | 5496 | ((Microelectromechanical adj Systems) or MEMS)  | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB |
| 2  | BRS  | 1237 | cleavage adj plane  | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB |
| 3  | BRS  | 11   | ((Microelectromechanical adj Systems) or MEMS) and (cleavage adj plane)   | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB |
| 4  | BRS  | 72   | ((Microelectromechanical adj Systems) or MEMS) and cleavage) and orient\$5  | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB |
| 5  | BRS  | 40   | ((Microelectromechanical adj Systems) or MEMS) and cleavage) and orient\$5) and (opening or cavity)                         | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB |
| 6  | BRS  | 3    | ((Microelectromechanical adj Systems) or MEMS) and cleavage) and orient\$5) and wafer with (opening or cavity)              | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB |
| 7  | BRS  | 130  | ((Microelectromechanical adj Systems) or MEMS) and cleavage   | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB |
| 8  | BRS  | 278  | ((Microelectromechanical adj Systems) or MEMS) and wafer with (opening or cavity)   | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB |
| 9  | BRS  | 96   | ((Microelectromechanical adj Systems) or MEMS) and wafer with (opening or cavity)) and orient\$5                            | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB |
| 10 | BRS  | 19   | (photolithography same mask) and (etch\$3 same wafer) and (mask same angle same rotat\$3)                                   | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB |
| 11 | BRS  | 14   | (wafer same photolithography) and (photolithography same mask) and (etch\$3 same wafer) and (mask same angle same rotat\$3) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB |
| 12 | BRS  | 1    | (wafer same photolithography) and (photolithography same mask) and (etch\$3 same wafer) and (contact adj printing adj step) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB |
| 13 | BRS  | 37   | (wafer same photolithography) and (photolithography same mask) and (etch\$3 same wafer) and (contact adj printing)          | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB |

|    | Time Stamp          | Comments | Error Definition | Errors |
|----|---------------------|----------|------------------|--------|
| 1  | 2003/03/17<br>17:32 |          |                  | 0      |
| 2  | 2003/03/17<br>17:13 |          |                  | 0      |
| 3  | 2003/03/17<br>17:22 |          |                  | 0      |
| 4  | 2003/03/17<br>17:50 |          |                  | 0      |
| 5  | 2003/03/17<br>17:29 |          |                  | 0      |
| 6  | 2003/03/17<br>17:40 |          |                  | 0      |
| 7  | 2003/03/17<br>17:33 |          |                  | 0      |
| 8  | 2003/03/17<br>17:41 |          |                  | 0      |
| 9  | 2003/03/17<br>17:50 |          |                  | 0      |
| 10 | 2003/03/18<br>13:25 |          |                  | 0      |
| 11 | 2003/03/18<br>14:06 |          |                  | 0      |
| 12 | 2003/03/18<br>14:08 |          |                  | 0      |
| 13 | 2003/03/18<br>14:08 |          |                  | 0      |